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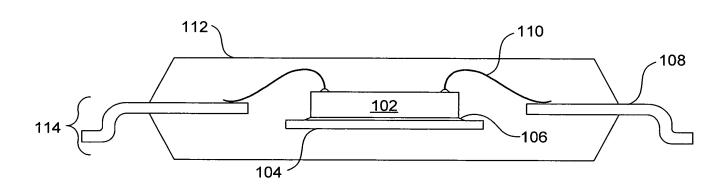


FIG. 1A

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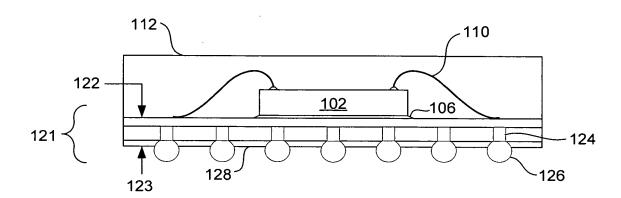


FIG. 1B

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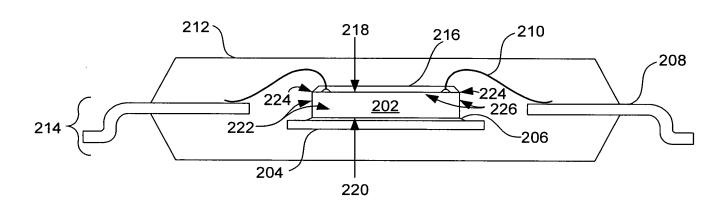


FIG. 2

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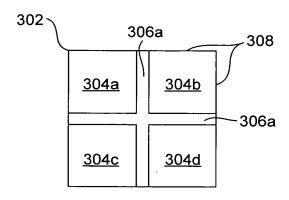


FIG. 3A

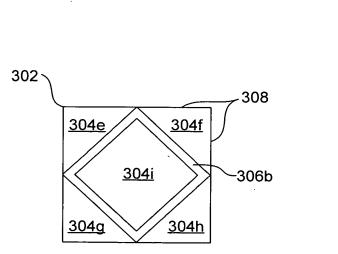


FIG. 3B

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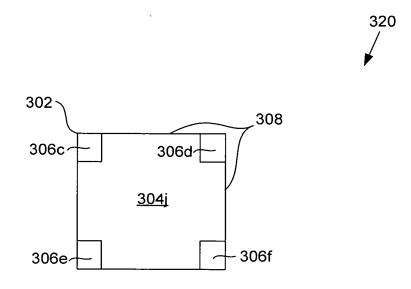


FIG. 3C

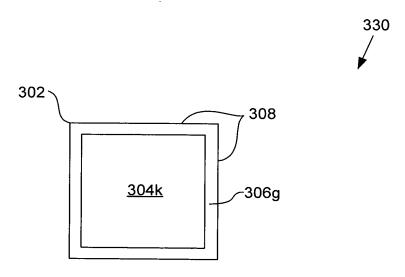


FIG. 3D

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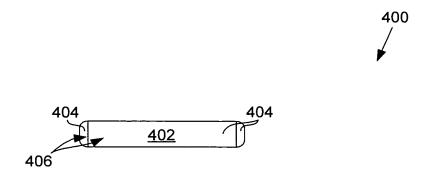


FIG. 4A



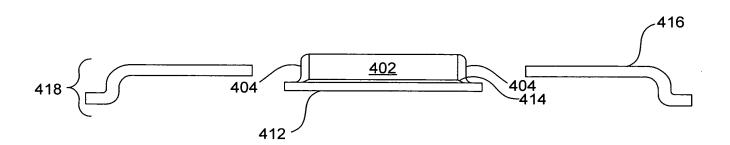


FIG. 4B

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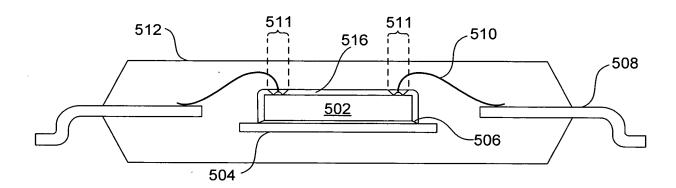


FIG. 5

Inventors: Wen-chou Vincent Wang et al.

Title: Structure, Material, And Design For Assembling A Low-K Si Die To Achieve An Industrial Grade Reliability Wire Bonding Package

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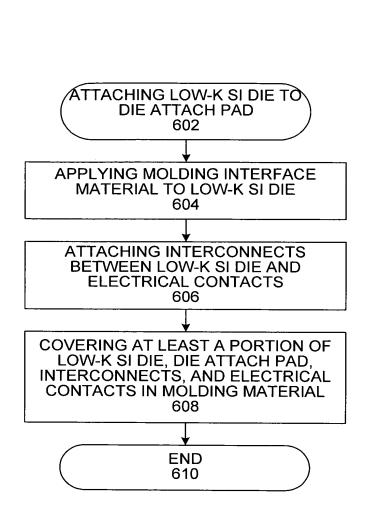


FIG. 6